

MSP430FW427 Device Erratasheet

1 Functional Errata Revision History

Errata impacting device's operation, function or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev E	Rev C
FLL3	✓	✓
PORT4		✓
PORT5		✓
PORT7		✓
SIF1	✓	✓
SIF2	✓	✓
SIF3	✓	✓
SIF4	✓	✓
TA12	✓	✓
TA16	✓	✓
TA21	✓	✓
TAB22	✓	✓
WDG2	✓	✓
XOSC9	✓	✓

2 Preprogrammed Software Errata Revision History

Errata impacting pre-programmed software into the silicon by Texas Instruments.

✓ The check mark indicates that the issue is present in the specified revision.

The device doesn't have Software in ROM errata.

3 Debug only Errata Revision History

Errata only impacting debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev E	Rev C
EEM20	✓	✓

4 Fixed by Compiler Errata Revision History

Errata completely resolved by compiler workaround. Refer to specific erratum for IDE and compiler versions with workaround.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev E	Rev C
CPU4	✓	✓

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

TI MSP430 Compiler Tools (Code Composer Studio IDE)

- [MSP430 Optimizing C/C++ Compiler](#): Check the --silicon_errata option
- [MSP430 Assembly Language Tools](#)

MSP430 GNU Compiler (MSP430-GCC)

- [MSP430 GCC Options](#): Check -msilicon-errata= and -msilicon-errata-warn= options
- [MSP430 GCC User's Guide](#)

IAR Embedded Workbench

- [IAR workarounds for msp430 hardware issues](#)

5 Package Markings

PM64

LQFP (PM), 64 Pin



= Die revision
○ = Pin 1 location
N = Lot trace code

6 Detailed Bug Description

CPU4 *CPU Module*

Category Compiler-Fixed

Function PUSH #4, PUSH #8CPU4 - Bug

Description The single operand instruction PUSH cannot use the internal constants (CG) 4 and 8. The other internal constants (0, 1, 2, -1) can be used. The number of clock cycles is different:

PUSH #CG uses address mode 00, requiring 3 cycles, 1 word instruction

PUSH #4/#8 uses address mode 11, requiring 5 cycles, 2 word instruction

Workaround Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v2.x until v6.20	User is required to add the compiler flag option below. --hw_workaround=CPU4
IAR Embedded Workbench	IAR EW430 v6.20 or later	Workaround is automatically enabled
TI MSP430 Compiler Tools (Code Composer Studio)	v1.1 or later	
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

EEM20 *EEM Module*

Category Debug

Function Debugger might clear interrupt flags

Description During debugging read-sensitive interrupt flags might be cleared as soon as the debugger stops. This is valid in both single-stepping and free run modes.

Workaround None.

FLL3 *FLL+ Module*

Category Functional

Function FLLDx = 11 for /8 may generate an unstable MCLK frequency

Description When setting the FLL to higher frequencies using FLLDx = 11 (/8) the output frequency of the FLL may have a larger frequency variation (e.g. averaged over 2sec) as well as a lower average output frequency than expected when compared to the other FLLDx bit settings.

Workaround None

PORT4 *PORT Module*

Category Functional

Function	SIF clock output depends on P2.7 AND P3.0
Description	The SIF - clock output is not available at port P2.7 when setting P2.7 as secondary function and output as described in data sheet
Workaround	Also set P3.0 to alternate function and output. The SIF clock signal is then available at P2.7.

PORT5 *PORT Module*

Category	Functional
Function	SIF comparator output is not available at P6.3
Description	The SIF comparator output is not available at port P6.3 when setting P6.3 as secondary function and output as described in data sheet
Workaround	None

PORT7 *PORT Module*

Category	Functional
Function	SIFDAC output function not available at P6.6
Description	The SIFDAC output is not available at port P6.6 when setting P6.6 as secondary function and output as described in data sheet
Workaround	None

SIF1 *SCANIF Module*

Category	Functional
Function	SIFCLK and MCLK dependency
Description	When the CPU clock source MCLK is faster than the SIF clock source SIFCLK, the PSM processing state-machine output register can become corrupted and result in incorrect SIFCNT operation.
Workaround	None. Ensure that the MCLK frequency is slower than or equal to the frequency of SIFCLK.

SIF2 *SCANIF Module*

Category	Functional
Function	SIFACLK and TSM0 dependency
Description	When the SIFACLK bit for the TSM0 state is set, the behavior of the TSM state machine can be unpredictable.
Workaround	Don't set SIFACLK in TSM0. This shortens the duration of the TSM0 state only. If the duration of TSM0 is of concern for an application, insert a dummy state at TSM0 with a

cleared SIFACLK bit and use TSM1 as the first valid user state.

SIF3
SCANIF Module

Category

Functional

Function

Bit SIFCACI3 cleared results in unexpected signal value if SIFCI is configured as input

Description

When SIFCI is configured as input for Scan IF by setting SIFCISEL bit, SIFCACI3 bit should be a don't care. However, clearing it will cause wrong scanned signal value.

Workaround

Set SIFCACI3 Bit (in SIFCTL2 register) if SIFCI is configured as input for Scan IF.

SIF4
SCANIF Module

Category

Functional

Function

Unpredictable CPU behavior if SMCLK (DCO) is used by SCAN IF and interrupts are enabled

Description

If the SCAN module is configured using the SMCLK (DCO) while CPU is in LPMx and any interrupt is enabled, unexpected short pulses of DCO clock (visible on MCLK) might occur. This rare scenario is triggered if an interrupt is fired during a small time window (hundreds of ps) after the Timing State Machine (TSM) of SCAN IF is releasing its clock request. Because of unexpected short pulses on MCLK, the behavior of CPU is unpredictable potentially leading to a non-responding device.

Workaround

Use the SCAN IF internal oscillator instead of SMCLK as the clock source for SCAN IF.

TA12
TIMER_A Module

Category

Functional

Function

Interrupt is lost (slow ACLK)

Description

Timer_A counter is running with slow clock (external TACLK or ACLK) compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by one with the occurring compare interrupt (if TAR = CCRx). Due to the fast MCLK the CCRx register increment (CCRx = CCRx+1) happens before the Timer_A counter has incremented again. Therefore the next compare interrupt should happen at once with the next Timer_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.

Workaround

Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

TA16
TIMER_A Module

Category

Functional

Function

First increment of TAR erroneous when IDx > 00

Description

The first increment of TAR after any timer clear event (POR/TACLK) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.

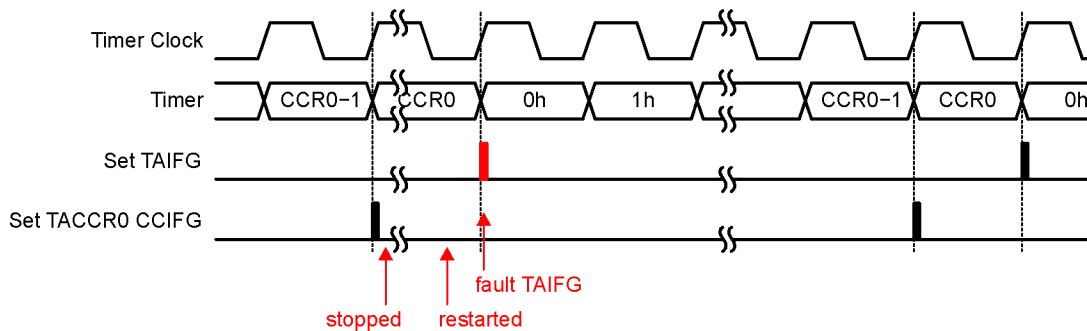
Workaround None

TA21 *TIMER_A Module*

Category Functional

Function TAIFG Flag is erroneously set after Timer A restarts in Up Mode

Description In Up Mode, the TAIFG flag should only be set when the timer counts from TACCR0 to zero. However, if the Timer A is stopped at TAR = TACCR0, then cleared (TAR=0) by setting the TACLK bit, and finally restarted in Up Mode, the next rising edge of the TACLK will erroneously set the TAIFG flag.



Workaround None.

TAB22 *TIMER_A/TIMER_B Module*

Category Functional

Function Timer_A/Timer_B register modification after Watchdog Timer PUC

Description Unwanted modification of the Timer_A/Timer_B registers TACTL/TBCTL and TAIV/TBIV can occur when a PUC is generated by the Watchdog Timer(WDT) in Watchdog mode and any Timer_A/Timer_B counter register TACCRx/TBCCRx is incremented/decremented (Timer_A/Timer_B does not need to be running).

Workaround Initialize TACTL/TBCTL register after the reset occurs using a MOV instruction (BIS/BIC may not fully initialize the register). TAIV/TBIV is automatically cleared following this initialization.

Example code:

```
MOV.W #VAL, &TACTL
```

or

```
MOV.W #VAL, &TBCTL
```

Where, VAL=0, if Timer is not used in application otherwise, user defined per desired function.

WDG2 *WDT Module*

Category Functional

Function	Incorrectly accessing a flash control register
Description	If a key violation is caused by incorrectly accessing a flash control register, the watchdog interrupt flag is set in addition to the expected PUC.
Workaround	None
XOSC9	<i>XOSC Module</i>
Category	Functional
Function	XT1 Oscillator may not function as expected in HF mode
Description	XT1 oscillator does not work correctly in high frequency mode at supply voltages below 2.0V with crystal frequency > 4MHz.
Workaround	None. When XT1 oscillator is used in HF mode with crystal frequency > 4MHz ensure a supply voltage > 2.2V.

7 Document Revision History

Changes from family erratasheet to device specific erratasheet.

1. Revision D was removed

Changes from device specific erratasheet to document Revision A.

1. Errata EEM20 was added to the errata documentation.

Changes from document Revision A to Revision B.

1. Errata TA21 was added to the errata documentation.

Changes from document Revision B to Revision C.

1. Errata SIF4 was added to the errata documentation.

Changes from document Revision C to Revision D.

1. Package Markings section was updated.

Changes from document Revision D to Revision E.

1. TA21 Description was updated.

Changes from document Revision E to Revision F.

1. Function for CPU4 was updated.
2. Workaround for CPU4 was updated.

Changes from document Revision F to Revision G.

1. Erratasheet format update.
2. Added errata category field to "Detailed bug description" section

IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>), [evaluation modules](#), and [samples](http://www.ti.com/sc/docs/sampterm.htm) (<http://www.ti.com/sc/docs/sampterm.htm>).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated